

REMARKS

The present Amendment is in response to an Office Action mailed May 14, 2004 in the above-identified application. Enclosed herewith is a Petition requesting a two-month extension of time for resetting the deadline for responding to the Office Action from August 14, 2004 to and including October 14, 2004.

As an initial matter, Applicant acknowledges and appreciates the Examiner's allowance of claims 15-24.

In the present Amendment, Applicant has amended claims 1, 3-4, 7 and 10. Claims 7 and 10 have been amended to address antecedent basis issues. Claims 1, 3 and 4 have been amended to introduce the concept that the dielectric layer is "adhered" to the microelectronic elements. Support for the amendment of claims 1, 3 and 4 is found in the specification at, *inter alia*, ¶ [0050] of the present application.

In the Office Action, the Examiner objected to the Abstract of the Disclosure as having legal phraseology. In response, Applicant has amended the Abstract to remove any legal phraseology. As amended, the Abstract is deemed to satisfy the requirements of M.P.E.P. Section 608.01(b).

In the Office Action, the Examiner also objected to the drawings. In response, Applicant has added text to paragraph 43 of the specification to describe layers 11, 13 in FIG. 2. Applicant has also amended FIGS. 6 and 8 to remove reference numerals 34 and 55, respectively, therefrom. Moreover, Applicant encloses herewith replacement drawing sheets for FIGS. 1-17.

The Examiner has rejected claims 1-14 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,518,964 to DiStefano et al. Referring to FIGS. 15-18 thereof, DiStefano discloses a process of using conductive leads 60 for electrically connecting a microelectronic element 86 to a dielectric sheet 34 and then moving the microelectronic element and the dielectric sheet away from one another for deforming the leads 60. A curable encapsulant material 108 is introduced

IN THE DRAWINGS

Applicant submits six (6) replacement drawing sheets.

Attachment: 6 Replacement Sheets

between the microelectronic element 86 and the dielectric sheet 34. Referring to FIG. 18, the electrically interconnected microelectronic element 86 and the dielectric sheet 34 are severed to produce individual microelectronic assemblies.

In contrast, in certain preferred embodiments of the present invention (FIGS. 1-8), a dielectric layer 20 has an inner region 22 and two outer regions 24, 26 that are covered by respective protective layers 28, 30. Referring to FIG. 4, after protective layer 28 is removed to expose the outer region 24 of dielectric layer 20, a microelectronic element 10 is abutted against the outer region 24 for adhering the dielectric layer 20 to the microelectronic element 10.

Claim 1 is unanticipated by DiStefano because the cited reference does not teach a method of making a microelectronic assembly including "adhering a dielectric layer to said plurality of microelectronic elements." As noted above, DiStefano's dielectric sheet 34 is electrically interconnected with the microelectronic element 86, but is not "adhered" to the microelectronic element 86. For these reasons, claim 1 is unanticipated by DiStefano and is otherwise allowable.

Claim 3 is unanticipated by DiStefano because the cited reference does not disclose a method of making a microelectronic assembly whereby the "adhering step includes providing said dielectric layer having a first major face, a second major face, a protective film over the first major face, and a second protective film over the second major face." Claim 3 is also unanticipated, *inter alia*, by virtue of its dependence from claim 1, which is unanticipated for the reasons set forth above.

Claim 4 is unanticipated by DiStefano because the cited reference does not disclose a method of making a microelectronic assembly including "providing a first adhesive on the first major face of said dielectric layer, wherein the adhering step comprises removing the first protective liner for exposing the first adhesive and abutting the first major face of said dielectric layer against said plurality of microelectronic

elements." Claim 4 is also unanticipated, *inter alia*, by virtue of its dependence from claim 3, which is unanticipated for the reasons set forth above.

Claims 2 and 5-13 are unanticipated, *inter alia*, by virtue of their dependence from claim 1, which is unanticipated for the reasons set forth above.

Claim 14 is unanticipated by DiStefano because the cited reference neither discloses nor suggests a method of making a microelectronic assembly including "providing an adhesive on the first major face of said dielectric layer [which] includes applying a flowable material to the plurality of microelectronic elements and at least partially curing the flowable material so that a layer of a partially cured, adhesive material is disposed on an outer surface of said dielectric layer." Claim 14 is also unanticipated, *inter alia*, by virtue of its dependence from claim 4, which is unanticipated for the reasons set forth above.

As it is believed that all of the rejections set forth in the Official Action have been fully met, favorable reconsideration and allowance are earnestly solicited.

If, however, for any reason the Examiner does not believe that such action can be taken at this time, it is respectfully requested that he telephone Applicant's attorney at (908) 654-5000 in order to overcome any additional objections which he might have.

If there are any additional charges in connection with this requested Amendment, the Examiner is authorized to charge Deposit Account No. 12-1095 therefor.

Dated: October 21, 2004

Respectfully submitted,

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